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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HABA et al.

Serial No.: 09/888,642

Filed: June 26, 2001

For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR INTEGRATED

Art Unit: 1753

Examiner: E. Wong

4/A
10.11.
10/2/03

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 22, 2003

Sir:

In response to the Office Action mailed August 20, 2003, please amend the
above-identified application as listed in the following and as set forth on the following
pages:

Amendments to the Claims**Remarks** are included following the amendments.